

LISTING OF THE CLAIMS

1-11 (Canceled)

12. (Previously Presented) A method for manufacturing an active panel of a liquid crystal display device, comprising steps of:

providing a transparent substrate;

fabricating a plurality of gate and source lines above the transparent substrate, each line having a pad;

forming a first layer above the transparent substrate to cover at least a portion of the transparent substrate, wherein the first layer exposes the pad of the each line and defines at least one opening near the pad, the opening having a depth lower than the surface of the first layer; and

forming a second layer having a first part and a second part, wherein the first part is affixed to the pad to provide an electrical signal to the line and the second part is affixed to a bottom surface of the opening defined in the first layer to enhance adhesion between the first and second layers.

13. (Original) The method of claim 12, wherein the first part of the second layer is a conductive portion and the second part is an insulating portion.

14. (Original) The method of claim 12, further including forming a third layer between the second layer and the first layer, wherein, the third layer affixes the first part to the pad and the second part to the substrate through the at least one opening defined in the first layer.

15. (Original) The method of claim 13, further including:

forming a third layer disposed between the second layer and the first layer, wherein the third layer affixes the conductive portion to the pad and the insulating portion to the substrate through the at least one opening defined in the first layer.

16. (Original) The method of claim 13, wherein the second layer is a tape carrier package.
17. (Original) The method of claim 14, wherein the third layer is an anisotropic conductive film.
18. (Original) The method of claim 12, wherein the at least one opening defined in the first layer is fabricated to extend to the substrate.
19. (Original) The method of claim 12, wherein the first layer defines a plurality of openings for securing the second layer above the first layer.
20. (Original) The method of claim 18, further including forming a third layer between the second layer and the first layer, wherein the third layer affixes the first part to the pad and the second part to the substrate through at least one opening defined in the first layer.